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Product Change Notification - JAON-29UXDQ760

Date: 06 Jun 2016

Product Category: 16-bit Microcontrollers and Digital Signal Controllers; Touch Sensing Technologies; 8-bit Microcontrollers; 32-bit PIC Microcontrollers

Notification subject: CCB 1751 and 1751.01 Cancellation Notice: For the qualification of CuPdAu bond wire in selected products of the 0.18um TSMC CUP wafer technology available in 64L and 44L TQFP (10x10mm) package at MTAI

Notification text: **PCN Status:**
Cancellation notification

Microchip Parts Affected:

This change would have affected selected products of the 0.18um TSMC CUP wafer technology available in 64L and 44L TQFP (10x10mm) package at MTAI assembly site.

Description of Change:

This qualification was originally performed to qualify palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.18um TSMC CUP wafer technology available in 64L and 44L TQFP (10x10mm) package at MTAI assembly site.

Impacts to Data Sheet:

Not Applicable

Reason for Change:

Microchip has decided not to qualify palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.18um TSMC CUP wafer technology available in 64L and 44L TQFP (10x10mm) package at MTAI assembly site.

Change Implementation Status:

Not Applicable

Estimated First Ship Date:

Not Applicable

Markings to Distinguish Revised from Unrevised Devices:

Not Applicable

Revision History:

October 14, 2015: Issued initial notification.

January 21, 2016: Revised the estimated first ship date from November 30, 2015 to April 20, 2016.

June 6, 2016: Issued cancellation notice for the proposed qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.18um TSMC CUP wafer technology available in 64L and 44L TQFP (10x10mm) package at MTAI assembly site.

Attachment(s): [PCN_JAON-29UXDQ760_Affected_CPN.pdf](#)
[PCN_JAON-29UXDQ760_Affected_CPN.xls](#)

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JAON-29UXDQ760 - CCB 1751 and 1751.01 Initial Notice: Qualification of CuPdAu wire in selected products of the 0.18um TSMC CUP wafer technology available in 64L and 44L TQFP (10x10mm) package at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-29UXDQ760
CATALOG_PART_NBR
DSPIC33EP128GM304-E/PT
DSPIC33EP128GM304-H/PT
DSPIC33EP128GM304-I/PT
DSPIC33EP128GM304T-I/PT
DSPIC33EP128GM306-E/PT
DSPIC33EP128GM306-H/PT
DSPIC33EP128GM306-I/PT
DSPIC33EP128GM306T-I/PT
DSPIC33EP128GM604-E/PT
DSPIC33EP128GM604-H/PT
DSPIC33EP128GM604-I/PT
DSPIC33EP128GM604T-I/PT
DSPIC33EP128GM706-E/PT
DSPIC33EP128GM706-H/PT
DSPIC33EP128GM706-I/PT
DSPIC33EP128GM706T-I/PT
DSPIC33EP128GP504-E/PT
DSPIC33EP128GP504-H/PT
DSPIC33EP128GP504-I/PT
DSPIC33EP128GP504-I/PTA3
DSPIC33EP128GP504T-I/PT
DSPIC33EP128GP506-E/PT
DSPIC33EP128GP506-H/PT
DSPIC33EP128GP506-I/PT
DSPIC33EP128GP506-I/PTA3
DSPIC33EP128GP506T-I/PT
DSPIC33EP128MC204-E/PT
DSPIC33EP128MC204-H/PT
DSPIC33EP128MC204-I/PT
DSPIC33EP128MC204-I/PTA3
DSPIC33EP128MC204T-I/PT
DSPIC33EP128MC204T-I/PTA3
DSPIC33EP128MC206-E/PT
DSPIC33EP128MC206-H/PT
DSPIC33EP128MC206-I/PT
DSPIC33EP128MC206-I/PTA3
DSPIC33EP128MC206T-E/PT
DSPIC33EP128MC206T-I/PT
DSPIC33EP128MC206T-I/PTA3
DSPIC33EP128MC504-E/PT
DSPIC33EP128MC504-H/PT
DSPIC33EP128MC504-I/PT
DSPIC33EP128MC504-I/PTA3
DSPIC33EP128MC504T-I/PT

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Affected Catalog Part Numbers (CPN)

PCN_JAON-29UXDQ760
CATALOG_PART_NBR
DSPIC33EP128MC506-E/PT
DSPIC33EP128MC506-E/PTC01
DSPIC33EP128MC506-H/PT
DSPIC33EP128MC506-I/PT
DSPIC33EP128MC506-I/PTA3
DSPIC33EP128MC506-I/PTC02
DSPIC33EP128MC506T-E/PTC01
DSPIC33EP128MC506T-I/PT
DSPIC33EP128MC506T-I/PTC02
DSPIC33EP16GS504-E/PT
DSPIC33EP16GS504-I/PT
DSPIC33EP16GS504T-E/PT
DSPIC33EP16GS504T-I/PT
DSPIC33EP16GS506-E/PT
DSPIC33EP16GS506-I/PT
DSPIC33EP16GS506T-E/PT
DSPIC33EP16GS506T-I/PT
DSPIC33EP256GM304-E/PT
DSPIC33EP256GM304-H/PT
DSPIC33EP256GM304-I/PT
DSPIC33EP256GM304T-I/PT
DSPIC33EP256GM306-E/PT
DSPIC33EP256GM306-H/PT
DSPIC33EP256GM306-I/PT
DSPIC33EP256GM306T-I/PT
DSPIC33EP256GM604-E/PT
DSPIC33EP256GM604-H/PT
DSPIC33EP256GM604-I/PT
DSPIC33EP256GM604T-I/PT
DSPIC33EP256GM706-E/PT
DSPIC33EP256GM706-H/PT
DSPIC33EP256GM706-I/PT
DSPIC33EP256GM706T-I/PT
DSPIC33EP256GP504-E/PT
DSPIC33EP256GP504-H/PT
DSPIC33EP256GP504-I/PT
DSPIC33EP256GP504T-E/PT
DSPIC33EP256GP504T-I/PT
DSPIC33EP256GP506-E/PT
DSPIC33EP256GP506-H/PT
DSPIC33EP256GP506-I/PT
DSPIC33EP256GP506T-E/PT
DSPIC33EP256GP506T-H/PT
DSPIC33EP256GP506T-I/PT

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Affected Catalog Part Numbers (CPN)

PCN_JAON-29UXDQ760
CATALOG_PART_NBR
DSPIC33EP256MC204-E/PT
DSPIC33EP256MC204-H/PT
DSPIC33EP256MC204-I/PT
DSPIC33EP256MC204T-E/PT
DSPIC33EP256MC204T-I/PT
DSPIC33EP256MC206-E/PT
DSPIC33EP256MC206-H/PT
DSPIC33EP256MC206-I/PT
DSPIC33EP256MC206-I/PTA3
DSPIC33EP256MC206T-E/PT
DSPIC33EP256MC206T-H/PT
DSPIC33EP256MC206T-I/PT
DSPIC33EP256MC206T-I/PTA3
DSPIC33EP256MC504-E/PT
DSPIC33EP256MC504-H/PT
DSPIC33EP256MC504-I/PT
DSPIC33EP256MC504T-E/PT
DSPIC33EP256MC504T-I/PT
DSPIC33EP256MC506-E/PT
DSPIC33EP256MC506-H/PT
DSPIC33EP256MC506-I/PT
DSPIC33EP256MC506T-E/PT
DSPIC33EP256MC506T-H/PT
DSPIC33EP256MC506T-I/PT
DSPIC33EP32GS504-E/PT
DSPIC33EP32GS504-I/PT
DSPIC33EP32GS504T-E/PT
DSPIC33EP32GS504T-E/PTC01
DSPIC33EP32GS504T-I/PT
DSPIC33EP32GS506-E/PT
DSPIC33EP32GS506-I/PT
DSPIC33EP32GS506T-E/PT
DSPIC33EP32GS506T-I/PT
DSPIC33EP512GM304-E/PT
DSPIC33EP512GM304-H/PT
DSPIC33EP512GM304-I/PT
DSPIC33EP512GM304T-I/PT
DSPIC33EP512GM306-E/PT
DSPIC33EP512GM306-H/PT
DSPIC33EP512GM306-I/PT
DSPIC33EP512GM306T-I/PT
DSPIC33EP512GM604-E/PT
DSPIC33EP512GM604-H/PT
DSPIC33EP512GM604-I/PT

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PCN_JAON-29UXDQ760
CATALOG_PART_NBR
DSPIC33EP512GM604T-I/PT
DSPIC33EP512GM706-E/PT
DSPIC33EP512GM706-H/PT
DSPIC33EP512GM706-I/PT
DSPIC33EP512GM706T-I/PT
DSPIC33EP512GP504-E/PT
DSPIC33EP512GP504-H/PT
DSPIC33EP512GP504-I/PT
DSPIC33EP512GP504T-E/PT
DSPIC33EP512GP504T-H/PT
DSPIC33EP512GP504T-I/PT
DSPIC33EP512GP506-E/PT
DSPIC33EP512GP506-H/PT
DSPIC33EP512GP506-I/PT
DSPIC33EP512GP506T-E/PT
DSPIC33EP512GP506T-H/PT
DSPIC33EP512GP506T-I/PT
DSPIC33EP512MC204-E/PT
DSPIC33EP512MC204-H/PT
DSPIC33EP512MC204-I/PT
DSPIC33EP512MC204T-E/PT
DSPIC33EP512MC204T-H/PT
DSPIC33EP512MC204T-I/PT
DSPIC33EP512MC206-E/PT
DSPIC33EP512MC206-H/PT
DSPIC33EP512MC206-I/PT
DSPIC33EP512MC206T-E/PT
DSPIC33EP512MC206T-H/PT
DSPIC33EP512MC206T-I/PT
DSPIC33EP512MC504-E/PT
DSPIC33EP512MC504-H/PT
DSPIC33EP512MC504-I/PT
DSPIC33EP512MC504T-E/PT
DSPIC33EP512MC504T-H/PT
DSPIC33EP512MC504T-I/PT
DSPIC33EP512MC506-E/PT
DSPIC33EP512MC506-H/PT
DSPIC33EP512MC506-I/PT
DSPIC33EP512MC506T-E/PT
DSPIC33EP512MC506T-H/PT
DSPIC33EP512MC506T-I/PT
DSPIC33EP64GP504-E/PT
DSPIC33EP64GP504-H/PT
DSPIC33EP64GP504-I/PT

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PCN_JAON-29UXDQ760
CATALOG_PART_NBR
DSPIC33EP64GP504-I/PTA3
DSPIC33EP64GP504T-E/PT
DSPIC33EP64GP504T-H/PT
DSPIC33EP64GP504T-I/PT
DSPIC33EP64GP506-E/PT
DSPIC33EP64GP506-H/PT
DSPIC33EP64GP506-I/PT
DSPIC33EP64GP506-I/PTA3
DSPIC33EP64GP506T-E/PT
DSPIC33EP64GP506T-H/PT
DSPIC33EP64GP506T-I/PT
DSPIC33EP64GS504-E/PT
DSPIC33EP64GS504-I/PT
DSPIC33EP64GS504T-E/PT
DSPIC33EP64GS504T-I/PT
DSPIC33EP64GS506-E/PT
DSPIC33EP64GS506-I/PT
DSPIC33EP64GS506T-E/PT
DSPIC33EP64GS506T-I/PT
DSPIC33EP64MC204-E/PT
DSPIC33EP64MC204-H/PT
DSPIC33EP64MC204-I/PT
DSPIC33EP64MC204-I/PTC02
DSPIC33EP64MC204T-E/PT
DSPIC33EP64MC204T-H/PT
DSPIC33EP64MC204T-I/PT
DSPIC33EP64MC204T-I/PTC01
DSPIC33EP64MC206-E/PT
DSPIC33EP64MC206-E/PTA8
DSPIC33EP64MC206-H/PT
DSPIC33EP64MC206-I/PT
DSPIC33EP64MC206-I/PTA3
DSPIC33EP64MC206T-E/PT
DSPIC33EP64MC206T-E/PTA8
DSPIC33EP64MC206T-H/PT
DSPIC33EP64MC206T-I/PT
DSPIC33EP64MC206T-I/PTA3
DSPIC33EP64MC504-E/PT
DSPIC33EP64MC504-H/PT
DSPIC33EP64MC504-I/PT
DSPIC33EP64MC504T-E/PT
DSPIC33EP64MC504T-H/PT
DSPIC33EP64MC504T-I/PT
DSPIC33EP64MC506-E/PT

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PCN_JAON-29UXDQ760
CATALOG_PART_NBR
DSPIC33EP64MC506-H/PT
DSPIC33EP64MC506-I/PT
DSPIC33EP64MC506T-E/PT
DSPIC33EP64MC506T-H/PT
DSPIC33EP64MC506T-I/PT
DSPIC33EV128GM004-E/PT
DSPIC33EV128GM004-H/PT
DSPIC33EV128GM004-I/PT
DSPIC33EV128GM004T-I/PT
DSPIC33EV128GM006-E/PT
DSPIC33EV128GM006-H/PT
DSPIC33EV128GM006-I/PT
DSPIC33EV128GM006T-I/PT
DSPIC33EV128GM104-E/PT
DSPIC33EV128GM104-H/PT
DSPIC33EV128GM104-I/PT
DSPIC33EV128GM104T-I/PT
DSPIC33EV128GM106-E/PT
DSPIC33EV128GM106-H/PT
DSPIC33EV128GM106-I/PT
DSPIC33EV128GM106T-I/PT
DSPIC33EV256GM004-E/PT
DSPIC33EV256GM004-H/PT
DSPIC33EV256GM004-I/PT
DSPIC33EV256GM004T-I/PT
DSPIC33EV256GM006-E/PT
DSPIC33EV256GM006-H/PT
DSPIC33EV256GM006-I/PT
DSPIC33EV256GM006T-I/PT
DSPIC33EV256GM104-E/PT
DSPIC33EV256GM104-H/PT
DSPIC33EV256GM104-I/PT
DSPIC33EV256GM104T-I/PT
DSPIC33EV256GM106-E/PT
DSPIC33EV256GM106-H/PT
DSPIC33EV256GM106-I/PT
DSPIC33EV256GM106T-I/PT
DSPIC33EV32GM004-E/PT
DSPIC33EV32GM004-H/PT
DSPIC33EV32GM004-I/PT
DSPIC33EV32GM004T-I/PT
DSPIC33EV32GM006-E/PT
DSPIC33EV32GM006-H/PT
DSPIC33EV32GM006-I/PT

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Affected Catalog Part Numbers (CPN)

PCN_JAON-29UXDQ760
CATALOG_PART_NBR
DSPIC33EV32GM006T-I/PT
DSPIC33EV32GM104-E/PT
DSPIC33EV32GM104-H/PT
DSPIC33EV32GM104-I/PT
DSPIC33EV32GM104T-I/PT
DSPIC33EV32GM106-E/PT
DSPIC33EV32GM106-H/PT
DSPIC33EV32GM106-I/PT
DSPIC33EV32GM106T-I/PT
DSPIC33EV64GM004-E/PT
DSPIC33EV64GM004-H/PT
DSPIC33EV64GM004-I/PT
DSPIC33EV64GM004T-I/PT
DSPIC33EV64GM006-E/PT
DSPIC33EV64GM006-H/PT
DSPIC33EV64GM006-I/PT
DSPIC33EV64GM006T-I/PT
DSPIC33EV64GM104-E/PT
DSPIC33EV64GM104-H/PT
DSPIC33EV64GM104-I/PT
DSPIC33EV64GM104T-I/PT
DSPIC33EV64GM106-E/PT
DSPIC33EV64GM106-H/PT
DSPIC33EV64GM106-I/PT
DSPIC33EV64GM106T-I/PT
MTCH6303-I/PT
MTCH6303T-I/PT
PIC18F65J94-I/PT
PIC18F65J94T-I/PT
PIC18F66J94-I/PT
PIC18F66J94T-I/PT
PIC18F67J94-I/PT
PIC18F67J94T-I/PT
PIC24EP128GP204-E/PT
PIC24EP128GP204-H/PT
PIC24EP128GP204-I/PT
PIC24EP128GP204-I/PT030
PIC24EP128GP204-I/PTA3
PIC24EP128GP204T-I/PT
PIC24EP128GP204T-I/PT030
PIC24EP128GP206-E/PT
PIC24EP128GP206-H/PT
PIC24EP128GP206-I/PT
PIC24EP128GP206-I/PTA3

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Affected Catalog Part Numbers (CPN)

PCN_JAON-29UXDQ760
CATALOG_PART_NBR
PIC24EP128GP206T-I/PT
PIC24EP128MC204-E/PT
PIC24EP128MC204-H/PT
PIC24EP128MC204-I/PT
PIC24EP128MC204-I/PTA3
PIC24EP128MC204T-I/PT
PIC24EP128MC206-E/PT
PIC24EP128MC206-H/PT
PIC24EP128MC206-I/PT
PIC24EP128MC206-I/PTA3
PIC24EP128MC206T-I/PT
PIC24EP256GP204-E/PT
PIC24EP256GP204-H/PT
PIC24EP256GP204-I/PT
PIC24EP256GP204T-E/PT
PIC24EP256GP204T-I/PT
PIC24EP256GP206-E/PT
PIC24EP256GP206-H/PT
PIC24EP256GP206-I/PT
PIC24EP256GP206T-E/PT
PIC24EP256GP206T-H/PT
PIC24EP256GP206T-I/PT
PIC24EP256MC204-E/PT
PIC24EP256MC204-H/PT
PIC24EP256MC204-I/PT
PIC24EP256MC204T-E/PT
PIC24EP256MC204T-I/PT
PIC24EP256MC206-E/PT
PIC24EP256MC206-H/PT
PIC24EP256MC206-I/PT
PIC24EP256MC206T-E/PT
PIC24EP256MC206T-H/PT
PIC24EP256MC206T-I/PT
PIC24EP512GP204-E/PT
PIC24EP512GP204-H/PT
PIC24EP512GP204-I/PT
PIC24EP512GP204T-E/PT
PIC24EP512GP204T-H/PT
PIC24EP512GP204T-I/PT
PIC24EP512GP206-E/PT
PIC24EP512GP206-H/PT
PIC24EP512GP206-I/PT
PIC24EP512GP206T-E/PT
PIC24EP512GP206T-H/PT

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Affected Catalog Part Numbers (CPN)

PCN_JAON-29UXDQ760
CATALOG_PART_NBR
PIC24EP512GP206T-I/PT
PIC24EP512MC204-E/PT
PIC24EP512MC204-H/PT
PIC24EP512MC204-I/PT
PIC24EP512MC204T-E/PT
PIC24EP512MC204T-H/PT
PIC24EP512MC204T-I/PT
PIC24EP512MC206-E/PT
PIC24EP512MC206-H/PT
PIC24EP512MC206-I/PT
PIC24EP512MC206T-E/PT
PIC24EP512MC206T-H/PT
PIC24EP512MC206T-I/PT
PIC24EP64GP204-E/PT
PIC24EP64GP204-H/PT
PIC24EP64GP204-I/PT
PIC24EP64GP204-I/PTA3
PIC24EP64GP204-I/PTC03
PIC24EP64GP204T-E/PT
PIC24EP64GP204T-H/PT
PIC24EP64GP204T-I/PT
PIC24EP64GP206-E/PT
PIC24EP64GP206-H/PT
PIC24EP64GP206-I/PT
PIC24EP64GP206-I/PTA3
PIC24EP64GP206T-E/PT
PIC24EP64GP206T-H/PT
PIC24EP64GP206T-I/PT
PIC24EP64MC204-E/PT
PIC24EP64MC204-H/PT
PIC24EP64MC204-I/PT
PIC24EP64MC204-I/PTC06
PIC24EP64MC204T-E/PT
PIC24EP64MC204T-H/PT
PIC24EP64MC204T-I/PT
PIC24EP64MC206-E/PT
PIC24EP64MC206-H/PT
PIC24EP64MC206-I/PT
PIC24EP64MC206T-E/PT
PIC24EP64MC206T-H/PT
PIC24EP64MC206T-I/PT
PIC24FJ128GA306-I/PT
PIC24FJ128GA306-I/PTC01
PIC24FJ128GA306-I/PTC06

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Affected Catalog Part Numbers (CPN)

PCN_JAON-29UXDQ760
CATALOG_PART_NBR
PIC24FJ128GA306-I/PTC09
PIC24FJ128GA306-I/PTREL
PIC24FJ128GA306T-I/PT
PIC24FJ128GA306T-I/PTC01
PIC24FJ128GA306T-I/PTC02
PIC24FJ128GA406-I/PT
PIC24FJ128GA406T-I/PT
PIC24FJ128GB406-I/PT
PIC24FJ128GB406T-I/PT
PIC24FJ256GA406-I/PT
PIC24FJ256GA406T-I/PT
PIC24FJ256GB406-I/PT
PIC24FJ256GB406T-I/PT
PIC24FJ64GA306-I/PT
PIC24FJ64GA306-I/PTC08
PIC24FJ64GA306-I/PTREL
PIC24FJ64GA306T-I/PT
PIC24FJ64GA306T-I/PT020
PIC24FJ64GA406-I/PT
PIC24FJ64GA406T-I/PT
PIC24FJ64GB406-I/PT
PIC24FJ64GB406T-I/PT
PIC32MX120F064H-50I/PT
PIC32MX120F064H-I/PT
PIC32MX120F064HT-50I/PT
PIC32MX120F064HT-I/PT
PIC32MX120F064HT-V/PT
PIC32MX120F064H-V/PT
PIC32MX130F128H-50I/PT
PIC32MX130F128H-I/PT
PIC32MX130F128HT-50I/PT
PIC32MX130F128HT-I/PT
PIC32MX130F128HT-V/PT
PIC32MX130F128H-V/PT
PIC32MX150F256H-50I/PT
PIC32MX150F256H-I/PT
PIC32MX150F256HT-50I/PT
PIC32MX150F256HT-I/PT
PIC32MX150F256HT-V/PT
PIC32MX150F256H-V/PT
PIC32MX170F512H-50I/PT
PIC32MX170F512H-I/PT
PIC32MX170F512HT-50I/PT
PIC32MX170F512HT-I/PT

JAON-29UXDQ760 - CCB 1751 and 1751.01 Initial Notice: Qualification of CuPdAu wire in selected products of the 0.18um TSMC CUP wafer technology available in 64L and 44L TQFP (10x10mm) package at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-29UXDQ760
CATALOG_PART_NBR
PIC32MX170F512HT-V/PT
PIC32MX170F512H-V/PT
PIC32MX230F128H-50I/PT
PIC32MX230F128H-I/PT
PIC32MX230F128HT-50I/PT
PIC32MX230F128HT-I/PT
PIC32MX230F128HT-V/PT
PIC32MX230F128H-V/PT
PIC32MX250F256H-50I/PT
PIC32MX250F256H-I/PT
PIC32MX250F256HT-50I/PT
PIC32MX250F256HT-I/PT
PIC32MX250F256HT-V/PT
PIC32MX250F256H-V/PT
PIC32MX270F512H-50I/PT
PIC32MX270F512H-I/PT
PIC32MX270F512HT-50I/PT
PIC32MX270F512HT-I/PT
PIC32MX270F512HT-V/PT
PIC32MX270F512H-V/PT
PIC32MX330F064H-I/PT
PIC32MX330F064HT-I/PT
PIC32MX330F064HT-V/PT
PIC32MX330F064H-V/PT
PIC32MX350F128H-I/PT
PIC32MX350F128HT-I/PT
PIC32MX350F128HT-V/PT
PIC32MX350F128H-V/PT
PIC32MX350F256H-I/PT
PIC32MX350F256HT-I/PT
PIC32MX350F256HT-V/PT
PIC32MX350F256H-V/PT
PIC32MX370F512H-I/PT
PIC32MX370F512HT-I/PT
PIC32MX370F512HT-V/PT
PIC32MX370F512H-V/PT
PIC32MX430F064H-I/PT
PIC32MX430F064HT-I/PT
PIC32MX430F064HT-V/PT
PIC32MX430F064H-V/PT
PIC32MX450F128H-I/PT
PIC32MX450F128HT-I/PT
PIC32MX450F128HT-V/PT
PIC32MX450F128H-V/PT

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Affected Catalog Part Numbers (CPN)

PCN_JAON-29UXDQ760
CATALOG_PART_NBR
PIC32MX450F256H-120/PT
PIC32MX450F256H-I/PT
PIC32MX450F256H-I/PTB21
PIC32MX450F256H-I/PTS21
PIC32MX450F256HT-120/PT
PIC32MX450F256HT-I/PT
PIC32MX450F256HT-V/PT
PIC32MX450F256H-V/PT
PIC32MX470F512H-120/PT
PIC32MX470F512H-I/PT
PIC32MX470F512HT-120/PT
PIC32MX470F512HT-I/PT
PIC32MX470F512HT-V/PT
PIC32MX470F512H-V/PT
PIC32MX530F128H-50I/PT
PIC32MX530F128H-I/PT
PIC32MX530F128HT-50I/PT
PIC32MX530F128HT-I/PT
PIC32MX530F128HT-V/PT
PIC32MX530F128H-V/PT
PIC32MX550F256H-50I/PT
PIC32MX550F256H-I/PT
PIC32MX550F256HT-50I/PT
PIC32MX550F256HT-I/PT
PIC32MX550F256HT-V/PT
PIC32MX550F256H-V/PT
PIC32MX570F512H-50I/PT
PIC32MX570F512H-I/PT
PIC32MX570F512HT-50I/PT
PIC32MX570F512HT-I/PT
PIC32MX570F512HT-V/PT
PIC32MX570F512H-V/PT